



NOTES:

- DIMENSIONING AND TOLERANCING PER
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.90	1.00	1.10
A1	0.00		0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.15 BSC		
D1	4.50	4.90	5.10
D2	3.50		4.22
Е	6.15 BSC		
E1	5.50	5.80	6.10
E2	3.45		4.30
е	1.27 BSC		
G	0.51	0.61	0.71
K	0.51		
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
М	3.00	3.40	3.80
θ	0 °		12 °

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location Α

= Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking.

8x k 0.10 C A B 0.05 C L	¬	
PIN 5 E2 (EXPOSED PAD)	BOTTOM VIEW	SOLDERING FOOTPRINT* M 1.270 4X -0.750 4X 1.000 0.965
STYLE 1: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN	STYLE 2: PIN 1. ANODE 2. ANODE 3. ANODE 4. NO CONNECT 5. CATHODE	1.330 0.905 0.495 3.200 4.530 0.475 4.530 4.530

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document versions are uncontrolled except	' '
NEW STANDARD:	REF TO JEDEC MO-240A	"CONTROLLED COPY" in red.	
DESCRIPTION:	DFN5 5X6, 1.27P (SO-8FL)		PAGE 1 OF 2



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